12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250514003.1
Qualification of RFAB using qualified Process Technology, Die Revision and Datasheet update for select devices
Change Notification / Sample Request

Date: May 19, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250514003.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM393AP	NULL
LM2903P	NULL
LM393P	LM393P
LM393PE4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250514003.1	PCN Date:	May 19, 2025
Title:	Qualification of RFAB using qualified Process Technology, Die Revision and Datasheet update for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	August 17, 2025	Sample requests accepted until:	July 18, 2025*

***Sample requests received after July 18, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the TIB qualified process technology and a die revision change for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
CFAB	JI3	200 mm	RFAB	TIB	300 mm

The die was also changed as a result of the process change.

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

TEXAS INSTRUMENTS — LM393B, LM2903B, LM193, LM293, LM293A, LM393, LM393A, LM2903, LM2903V
SLCS005AH – OCTOBER 1979 – REVISED APRIL 2025

Changes from Revision AG (January 2025) to Revision AH (April 2025) — **Page**

- Updated front page *Family Comparison Table* ESD specs 1
- Restored missing "P" package column in *Thermal Information* table 5

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
LM393B, LM2903B, LM193, LM293, LM393 and LM2903	SLCS005aG	**SLCS005aH**	http://www.ti.com/product/LM393B

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

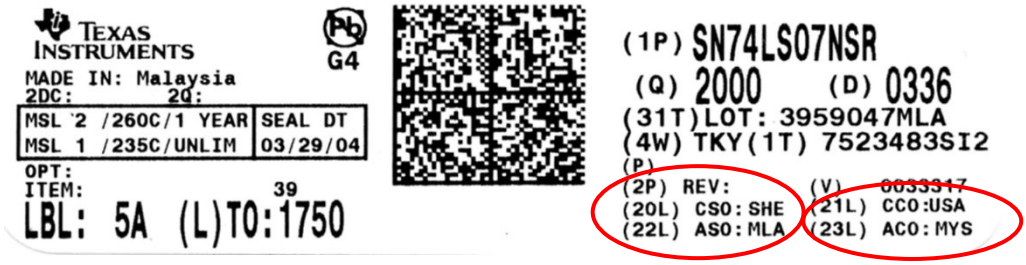
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
CFAB	CU3	CHN	Chengdu
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Sample product shipping label (not actual product label):



Product Affected:

LM2903P	LM393AP	LM393P	LM393PE4
LM293P			

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM393P	Qual Device: LM2903P	QBS Reference: NE5532P	QBS Reference: UCC37322P	QBS Reference: TL431BQDBZR	QBS Reference: SN74HC00N	QBS Reference: LM2903BIDR	QBS Reference: LM2903BQDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0	-	-	1/77/0
ESD	E2	ESD CDM	-	2000 Volts	-	-	-	-	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: LM393P	Qual Device: LM2903P	QBS Reference: NE5532P	QBS Reference: UCC37322P	QBS Reference: TL431BQDBZR	QBS Reference: SN74HC00N	QBS Reference: LM2903BIDR	QBS Reference: LM2903BQDRQ1
ESD	E2	ESD CDM	-	1000 Volts	-	1/3/0	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	1/3/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	-	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	-	Pass	-	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device LM393P is qualified at NOT CLASSIFIED 260C
- Qual Device LM2903P is qualified at NOT CLASSIFIED 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2310-101

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.